



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE7258SJ			<b>Issued</b>	19. July 2018			
<b>MA#</b>	MA001224024							
<b>Package</b>	PG-DSO-8-44			<b>Weight*</b>	82.63 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	1.00	1.00	10020	10020
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8680	
wire	non noble metal	copper	7440-50-8	29.121	35.24	36.16	352434	361657
	non noble metal	copper	7440-50-8	0.055	0.07	0.07	662	662
	plastics	epoxy resin	-	4.606	5.57		55745	
encapsulation	inorganic material	silicondioxide	60676-86-0	45.360	54.91		548961	
	organic material	carbon black	1333-86-4	0.100	0.12	60.60	1212	605918
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9849	9849
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7870	7870
glue	plastics	acrylic resin	-	0.073	0.09		885	
	noble metal	silver	7440-22-4	0.259	0.31	0.40	3139	4024
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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